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AT25SL321



32-Mbit, 1.7V Minimum SPI Serial Flash Memory with Dual I/O, Quad I/O and QPI Support

ADVANCE DATASHEET

Features

- Single 1.7V 2.0V Supply
- Serial Peripheral Interface (SPI) and Quad Peripheral Interface (QPI) Compatible
 - Supports SPI Modes 0 and 3
 - Supports Dual Output Read and Quad I/O Program and Read
 - Supports QPI Program and Read
 - 104 MHz* Maximum Operating Frequency
 - Clock-to-Output (t_{V1}) of 6 ns
 - Up tp 65MB/S continuous data transfer rate
- Full Chip Erase
- Flexible, Optimized Erase Architecture for Code and Data Storage Applications
 - 0.6 ms Typical Page Program (256 Bytes) Time
 - 60 ms Typical 4-Kbyte Block Erase Time
 - 200 ms Typical 32-Kbyte Block Erase Time
 - 300 ms Typical 64-Kbyte Block Erase Time
- Hardware Controlled Locking of Protected Blocks via WP Pin
- 4K-bit secured One-Time Programmable Security Register
- Hardware Write Protection
- Serial Flash Discoverable Parameters (SFDP) Register
- Flexible Programming
 - Byte/Page Program (1 to 256 Bytes)
 - Dual or Quad Input Byte/Page Program (1 to 256 Bytes)
 - Accelerated programming mode via 9V ACC pin
- Erase/Program Suspend and Resume
- JEDEC Standard Manufacturer and Device ID Read Methodology
- Low Power Dissipation
 - 2µA Deep Power-Down Current (Typical)
 - 10µA Standby current (Typical)
 - 5mA Active Read Current (Typical)
 - Endurance: 100,000 program/erase cycles (4KB, 32KB or 64KB blocks)
- Data Retention: 20 Years
- Industrial Temperature Range: -40°C to +85°C
- Industry Standard Green (Pb/Halide-free/RoHS Compliant) Package Options
 - 8-lead SOIC (208-mil)
 - 8-pad DFN (6 x 5 x 0.6 mm)
 - 24-ball Ball Grid Array (BGA)
 - 8 and 10-ball WLCSP, die Ball Grid Array (dBGA)
 - 8-pad USON(3 x 4 x 0.55mm)
 - Die in Wafer Form

1. Introduction

The Adesto[®] AT25SL321 is a serial interface Flash memory device designed for use in a wide variety of high-volume consumer based applications in which program code is shadowed from Flash memory into embedded or external RAM for execution. The flexible erase architecture of the AT25SL321 is ideal for data storage as well, eliminating the need for additional data storage devices.

The erase block sizes of the AT25SL321 have been optimized to meet the needs of today's code and data storage applications. By optimizing the size of the erase blocks, the memory space can be used much more efficiently. Because certain code modules and data storage segments must reside by themselves in their own erase regions, the wasted and unused memory space that occurs with large block erase Flash memory devices can be greatly reduced. This increased memory space efficiency allows additional code routines and data storage segments to be added while still maintaining the same overall device density.

SPI clock frequencies of up to 104MHz* are supported allowing equivalent clock rates of 266MHz for Dual Output and 532MHz for Quad Output when using the QPI and Fast Read Dual/Quad I/O instructions. The AT25SL321 array is organized into 65,536 programmable pages of 256-bytes each. Up to 256 bytes can be programmed at a time using the Page Program instructions. Pages can be erased 4KB Block, 32KB Block, 64KB Block or the entire chip.

The devices operate on a single 1.7V to 1.95V power supply with current consumption as low as 5mA active and 2μ A for Deep Power Down. All devices offered in space-saving packages. The device supports JEDEC standard manufacturer and device identification with a 4K-bit Secured OTP.

*Contact Adesto for availability of 133MHz operating frequency.



2. Pinouts and Pin Descriptions

The following figures show the available package types.



*Final package outline drawing to be confirmed.



During all operations, V_{CC} must be held stable and within the specified valid range: V_{CC} (min) to V_{CC} (max). All of the input and output signals must be held high or low (according to voltages of VIH, VOH, VIL or VOL.

Table 1-1. Pin Descriptions

Symbol	Name and Function	Asserted State	Туре
CS	CHIP SELECT When this input signal is high, the device is deselected and serial data output pins are at high impedance. Unless an internal program, erase or write status register cycle is in progress, the device will be in the standby power mode (this is not the deep power down mode). Driving Chip Select (CS) low enables the device, placing it in the active power mode. After power-up, a falling edge on Chip Select (CS) is required prior to the start of any instruction.	Low	Input
SCK	SERIAL CLOCK This input signal provides the timing for the serial interface. Instructions, addresses, or data present at serial data input are latched on the rising edge of Serial Clock (SCK). Data are shifted out on the falling edge of the Serial Clock (SCK).	-	Input
SI (I/O ₀)	 SERIAL INPUT The SI pin is used to shift data into the device. The SI pin is used for all data input including command and address sequences. Data on the SI pin is always latched in on the rising edge of SCK. With the Dual-Output and Quad-Output Read commands, the SI Pin becomes an output pin (I/O₀) in conjunction with other pins to allow two or four bits of data on (I/O₃₋₀) to be clocked in on every falling edge of SCK To maintain consistency with the SPI nomenclature, the SI (I/O₀) pin is referenced as the SI pin unless specifically addressing the Dual-I/O and Quad-I/O modes in which case it is referenced as I/O₀. Data present on the SI pin is ignored whenever the device is deselected (CS is deasserted). 	-	Input/Output
SO (I/O ₁)	SERIAL OUTPUT The SO pin is used to shift data out from the device. Data on the SO pin is always clocked out on the falling edge of SCK. With the Dual-Output Read commands, the SO Pin remains an output pin (I/O0) in conjunction with other pins to allow two bits of data on (I/O_{1-0}) to be clocked in on every falling edge of SCK To maintain consistency with the SPI nomenclature, the SO (I/O ₁) pin is referenced as the SO pin unless specifically addressing the Dual-I/O modes in which case it is referenced as I/O_1 . The SO pin is in a high-impedance state whenever the device is deselected (\overline{CS} is deasserted).	-	Input/Output



Table 1-1. Pin Descriptions (Continued)

Symbol	Name and Function	Asserted State	Туре
WP (I/O ₂)	WRITE PROTECT The Write Protect (WP) pin can be used to protect the Status Register against data modification. The WP pin is active low. When the QE bit of Status Register-2 is set for Quad I/O, the WP pin (Hardware Write Protect) function is not available since this pin is used for IO ₂ . See figures 1-1, 1-2, and 1-3 for the pin configuration of Quad I/O and QPI operation.	-	Input/Output
	ACCELERATED PROGRAMMING The device offers accelerated program operations through the ACC function. This function is primarily intended to allow faster manufacturing throughput at the factory.		
ACC	If the system asserts V_{HH} on this pin, the device uses the higher voltage on the pin to reduce the time required for program operations. Removing V_{HH} from the ACC pin returns the device to normal operation.		
AUC	Note that the ACC pin must not be at V_{HH} for operations other than accelerated programming, or device damage may result. In addition, the ACC pin must not be left floating or unconnected; inconsistent behavior of the device may result. The ACC function is only available during standard SPI Mode.		
	HOLD The HOLD pin is used to pause a serial sequence of the SPI flash memory without resetting the clocking sequence. To enable the HOLD mode, the CS must be in low state. The HOLD mode effects on with the falling edge of the HOLD signal with CLK being low. The HOLD mode ends on the rising edge of HOLD signal with SCK being low.		
HOLD (I/O ₃)	In other words, \overline{HOLD} mode can't be entered unless SCK is low at the falling edge of the \overline{HOLD} signal. And \overline{HOLD} mode can't be exited unless SCK is low at the rising edge of the HOLD signal.	-	Input/Output
	If $\overline{\text{CS}}$ is driven high during a $\overline{\text{HOLD}}$ condition, it resets the internal logic of the device. As long as HOLD signal is low, the memory remains in the $\overline{\text{HOLD}}$ condition. To re-work communication with the device, $\overline{\text{HOLD}}$ must go high, and $\overline{\text{CS}}$ must go low. See Figure 8.11 for $\overline{\text{HOLD}}$ timing.		
V _{cc}	DEVICE POWER SUPPLY: V _{CC} is the supply voltage. It is the single voltage used for all device functions including read, program, and erase. The V _{CC} pin is used to supply the source voltage to the device. Operations at invalid V _{CC} voltages may produce spurious results and should not be attempted.	-	Power
GND	GROUND: V_{SS} is the reference for the V_{CC} supply voltage. The ground reference for the power supply. GND should be connected to the system ground.	-	Power



2. Block Diagram

Figure 2-1 shows a block diagram of the AT25SL321 serial Flash.





Note: I/O₃₋₀ pin naming convention is used for Dual-I/O and Quad-I/O commands.



3. **Memory Array**

To provide the greatest flexibility, the memory array of the AT25SL321 can be erased in four levels of granularity including a full chip erase. The size of the erase blocks is optimized for both code and data storage applications, allowing both code and data segments to reside in their own erase regions. The Memory Architecture Diagram illustrates the breakdown of each erase level.

	Block E	rase Detail		Page Progra	am Detail
64KB	32KB	4KB		1-256 Byte	
			Block Address		Page Address
			Range		Range
		4KB	3FFFFFh – 3FF000h	256 Bytes	3FFFFFh – 3FFF00h
		4KB	3FEFFFh – 3FE000h	256 Bytes	3FFEFFh – 3FFE00h
		4KB	3FDFFFh – 3FD000h	256 Bytes	3FFDFFh – 3FFD00
	Block	4KB	3FCFFFh – 3FC000h	256 Bytes	3FFCFFh – 3FFC00ł
	127	4KB	3FBFFFh – 3FB000h	256 Bytes	3FFBFFh – 3FFB00h
		4KB	3FAFFFh – 3FA000h	256 Bytes	3FFAFFh – 3FFA00h
		4KB	3F9FFFh – 3F9000h	256 Bytes	3FF9FFh – 3FF900h
Sector 63		4KB	3F8FFFh – 3F8000h	256 Bytes	3FF8FFh – 3FF800h
Sector 05		4KB	3F7FFFh – 3F7000h	256 Bytes	3FF7FFh – 3FF700h
		4KB	3F6FFFh – 3F6000h	256 Bytes	3FF6FFh – 3FF600h
		4KB	3F5FFFh – 3F5000h	256 Bytes	3FF5FFh – 3FF500h
	Block	4KB	3F4FFFh – 3F4000h	256 Bytes	3FF4FFh – 3FF400h
	126	4KB	3F3FFFh – 3F3000h	256 Bytes	3FF3FFh - 3FF300h
		4KB	3F2FFFh – 3F2000h	256 Bytes	3FF2FFh – 3FF200h
		4KB	3F1FFFh – 3F1000h	256 Bytes	3FF1FFh - 3FF100h
		4KB	3F0FFFh - 3F0000h	256 Bytes	3FF0FFh - 3FF000h
	Block 125	4KB	3EFFFFh - 3EF000h	256 Bytes	3FEFFFh - 3FEF00h
		4KB	3EEFFFh - 3EE000h	256 Bytes	3FEEFFh - 3FEE00h
		4KB	3EDFFFN - 3ED000h	256 Bytes	3FEDFFN - 3FED00r
		4KB	JECFFFN - JECOUON	256 Bytes	3FECFFN - 3FECOUR
		4KB	JEBFFFN - JEBOUUN	256 Bytes	3FEBFFN - 3FEBUUN
		4KB	SEAFFFN - SEAUUUN	256 Bytes	
		4KB	259FFFII - 3590001	256 Bytes	2559551 - 3559000
Sector 62		4ND	3EZEEEb _ 3EZOO0b	230 Bytes	
		4KD	3E6EEEb _ 3E6000b	:	:
		4KB	3E5EEEb - 3E5000b	•	•
		4KB	3E4FEEb = 3E4000b	256 Bytes	
	Block 124	4KB	3E3EEEb = 3E3000b	256 Bytes	0016FEb - 001600b
		4KB	3E2EEEh = 3E2000h	256 Bytes	0015FFh - 001500h
		4KB	3E1FFFh - 3E1000h	256 Bytes	0014FFh - 001400h
		4KB	3E0FFFh - 3E0000h	256 Bytes	0013FFh - 001300h
				256 Bytes	0013FFh - 001300h
:	:	:		256 Bytes	0013FFh - 001300h
•	•	•		256 Bytes	0012FFh - 001200h
		4KB	00FFFFh-00F000h	256 Bytes	0011FFh - 001100h
		4KB	00EFFFh-00E000h	256 Bytes	0010FFh – 001000h
		4KB	00DFFFh-00D000h	256 Bytes	000FFFh - 000F00h
	Dia ali	4KB	00CFFFh-00C000h	256 Bytes	000CFFh - 000C00h
	BIOCK	4KB	00BFFFh-00B000h	256 Bytes	000BFFh - 000B00h
	I	4KB	00AFFFh-00A000h	256 Bytes	000AFFh – 000A00h
		4KB	009FFFh-009000h	256 Bytes	0009FFh – 000900h
Sector 0		4KB	008FFFh-008000h	256 Bytes	0008FFh – 000800h
Jector		4KB	007FFFh-007000h	256 Bytes	0007FFh – 000700h
		4KB	006FFFh-006000h	256 Bytes	0006FFh – 000600h
		4KB	005FFFh-005000h	256 Bytes	0005FFh – 000500h
	Block	4KB	004FFFh-004000h	256 Bytes	0004FFh – 000400h
	0	4KB	003FFFh-003000h	256 Bytes	0003FFh - 000300h
	-	4KB	002FFFh=002000h	256 Bytes	0002FFh - 000200h
		4KB	001FFFh-001000h	256 Bytes	0001FFh – 000100h
		4KB	000FFFh-000000h	256 Bytes	0000FFh - 000000h

Figure 3-1. Memory Architecture Diagram



7

4. Device Operation

4.1 Standard SPI Operation

The AT25SL321 features a serial peripheral interface on four signals: Serial Clock (SCK). Chip Select (\overline{CS}), Serial Data Input (SI) and Serial Data Output (SO). Standard SPI instructions use the SI input pin to serially write instructions, addresses or data to the device on the rising edge of SCK. The SO output pin is used to read data or status from the device on the falling edge of SCK.

SPI bus operation Modes 0 (0, 0) and 3 (1, 1) are supported. The primary difference between Mode 0 and Mode 3 concerns the normal state of the SCK signal when the SPI bus master is in standby and data is not being transferred to the Serial Flash. For Mode 0 the SCK signal is normally low on the falling and rising edges of \overline{CS} . For Mode 3 the SCK signal is normally high on the falling and rising edges of \overline{CS} .

4.2 Dual SPI Operation

The AT25SL321 supports Dual SPI operation. This instruction allows data to be transferred to or from the device at two times the rate of the standard SPI. The Dual Read instruction is ideal for quickly downloading code to RAM upon power-up (code-shadowing) or for executing non-speed- critical code directly from the SPI bus (XIP). When using Dual SPI instructions the SI and SO pins become bidirectional I/0 pins; IO_0 and IO_1 .

4.3 Quad SPI Operation

The AT25SL321 supports Quad SPI operation. This instruction allows data to be transferred to or from the device at four times the rate of the standard SPI. The Quad Read instruction offers a significant improvement in continuous and random access transfer rates allowing fast code- shadowing to RAM or execution directly from the SPI bus (XIP). When using Quad SPI instruction the SI and SO pins become bidirectional IO₀ and IO₁, and the WP and HOLD pins become IO₂ and IO₃ respectively. Quad SPI instructions require the non-volatile Quad Enable bit (QE) in Status Register-2 to be set.

4.4 QPI Operation

The AT25SL321 supports Quad Peripheral Interface (QPI) operation when the device is switched from Standard/ Dual/ Quad SPI mode to QPI mode using the "Enable QPI (38h)" instruction. To enable QPI mode, the non-volatile Quad Enable bit (QE) in Status Register-2 is required to be set. When using QPI instructions, the SI and SO pins become bidirectional IO0 and IO1, and the WP and HOLD pins become IO_2 and IO_3 respectively.

The typical SPI protocol requires that the byte-long instruction code being shifted into the device only via SI pin in eight serial clocks. The QPI mode utilizes all four IO pins to input the instruction code, thus only two serial clocks are required. This can significantly reduce the SPI instruction overhead and improve system performance in an XIP environment. Standard/ Dual/ Quad SPI mode and QPI mode are exclusive. Only one mode can be active at any given time, "Enable QPI" and "Disable QPI/ Disable QPI 2" instructions are used to switch between these two modes. Upon power-up or after software reset using "Reset (99h) instruction, the default state of the device is Standard/ Dual/ Quad SPI mode.



5. Write Protection

To protect inadvertent writes by the possible noise, several means of protection are applied to the Flash memory.

5.1 Write Protect Features

- While Power-on reset, all operations are disabled and no instruction is recognized.
- An internal time delay of tPUW can protect the data against inadvertent changes while the power supply is outside the operating specification. This includes the Write Enable, Page program, Block Erase, Chip Erase, Write Security Register and the Write Status Register instructions.
- For data changes, Write Enable instruction must be issued to set the Write Enable Latch (WEL) bit to "0". Powerup, Completion of Write Disable, Write Status Register, Page program, Block Erase and Chip Erase are subjected to this condition.
- Write Protect (WP) pin can control to change the Status Register under hardware control.
- The Deep Power Down mode provides extra protection from unexpected data changes as all instructions are ignored under this status except for Release Deep Power Down instruction.



6. Status Register

The Read Status Register instruction can be used to provide status on the availability of the Flash memory array, if the device is write enabled or disabled the state of write protection and the Quad SPI setting. The Write Status Register instruction can be used to configure the devices writes protection features and Quad SPI setting. Write access to the Status Register is controlled by in some cases of the WP pin.

S7	S6	S5	S4	S3	S2	S1	S0
SRP	(R)	(R)	(R)	(R)	(R)	WEL	BUSY
Status Register Protect 0 (Non- Volatile)	Reserved	Reserved	Reserved	Reserved	Reserved	Write Enable Latch	Erase or Write in Progress

Table 6-1. Status Register-1

Table 6-2. Status Register-2

S15	S14	S13	S12	S11	S10	S9	S8
SUS	(R)	(R)	(R)	(R)	(R)	QE	SRP1
Suspend Status	Reserved	Reserved	Reserved	Reserved	Reserved	Quad Enable (Non- Volatile)	Register Protect 1 (Non- Volatile)

6.1 Busy

BUSY is a read only bit in the status register (S0) that is set to a 1 state when the device is executing a Page Program, Erase, Write Status Register or Write Security Register instruction. During this time the device will ignore further instruction except for the Read Status Register and Erase / Program Suspend instruction (see tW, tPP, tSE, tBE1, tBE2 and tCE in AC Characteristics). When the Program, Erase, Write Status Register or Write Security Register instruction has completed, the BUSY bit will be cleared to a 0 state indicating the device is ready for further instructions.

6.2 Write Enable Latch (WEL)

Write Enable Latch (WEL) is a read only bit in the status register (S1) that is set to a 1 after executing a Write Enable instruction. The WEL status bit is cleared to a 0 when device is write disabled. A write disable state occurs upon power-up or after any of the following instructions: Write Disable, Page Program, Erase and Write Status Register.

6.3 Status Register Protect (SRP1, SRP0)

The Status Register Protect bits (SRP1 and SRP0) are non-volatile read/write bits in the status register (S8 and S7). The SRP bits control the method of write protection: software protection, hardware protection, power supply lock-down or one time programmable (OTP) protection.



SRP1	SRP 0	WP	Status Register	Description
0	0	х	Software	WP pin no control. The register can be written to
0	1	0	Hardware	When WP pin is low the Status Register locked and can not
0	1	1	Hardware Unprotected	When \overline{WP} pin is high the Status register is unlocked and can be written to after a Write Enable instruction, WEL=1
1	0	х	Power Supply	Status Register is protected and cannot be written to again until the next power down, power-up cycle(1)
1	1	х	One Time	Status Register is permanently protected and cannot be written to.

Note: 1. When SRP1, SRP0=(1,0), a power down, power-up cycle will change SRP1, SRP0 to(0,0) state.

6.4 Quad Enable (QE)

The Quad Enable (QE) bit is a non-volatile read/write bit in the status register (S9) that allows Quad operation. When the QE bit is set to a 0 state (factory default) the WP pin and HOLD are enabled. When the QE pin is set to a 1 the Quad IO2 and IO3 pins are enabled. WARNING : The QE bit should never be set to a 1 during standard SPI or Dual SPI operation if the WP or HOLD pins are tied directly to the power supply or ground.

6.5 Erase/Program Suspend Status (SUS)

The Suspend Status bit (SUS) is a read only bit in the status register (S15) that is set to 1 after executing an Erase/Program Suspend (75h) instruction. The SUS status bit is cleared to 0 by Erase/Program Resume (7Ah) instruction as well as a power down, power-up cycle.



7. Instructions

The SPI instruction set of the AT25SL321 consists of thirty eight basic instructions and the QPI instruction set of the AT25SL321 consists of thirty one basic instructions that are fully controlled through the SPI bus (see Instruction Set table). Instructions are initiated with the falling edge of Chip Select (\overline{CS}). The first byte of data clocked into the input pins (SI or IO [3:0]) provides the instruction code. Data on the SI input is sampled on the rising edge of clock with most significant bit (MSB) first.

Instructions are completed with the rising edge of edge \overline{CS} . Clock relative timing diagrams for each instruction are included in figures 8-1 through 8-66 All read instructions can be completed after any clocked bit. However, all instructions that Write, Program or Erase must complete on a byte (\overline{CS} driven high after a full 8-bit have been clocked) otherwise the instruction will be terminated. This feature further protects the device from inadvertent writes. Additionally, while the memory is being programmed or erased, or when the Status Register is being written, all instructions except for Read Register will be ignored until the program or erase cycle has completed.

Table 7-1. Manufacturer and Device Identification

		ID code	Instruction
Manufacturer ID	Adesto	1Fh	90h, 92h, 94h, 9Fh
Device ID	AT25SL321	15h	90h, 92h, 94h, ABh
Memory Type ID	SPI / QPI	42h	9Fh
Capacity Type ID	32M	16h	9Fh

7.1 Instruction Set Tables

Table 7-2. Instruction Set Table 1 (SPI instruction)⁽¹⁾

INSTRUCTION NAME	BYTE 1	BYTE 2	BYTE 3	BYTE 4	BYTE 5	BYTE 6
(CLOCK NUMBER)	(0 – 7)	(8 - 15)	(16 - 23)	(24 - 31)	(32 - 39)	(40 - 47)
Write Enable	06h					
Write Enable For Volatile	50h					
Write Disable	04h					
Read Status Register-1	05h	(SR7-SR0) ⁽²⁾				
Read Status Register-2	35h	(SR15-SR8) ⁽²⁾				
Write Status Register-1	01h	(SR7-SR0)	(SR15-SR8)			
Write Status Register-2	31h	(SR15-SR8)				
Read Data	03h	A23-A16	A15-A8	A7-A0	(D7-D0)	
Fast Read Data	0Bh	A23-A16	A15-A8	A7-A0	dummy	(D7-D0)
Page Program	02h	A23-A16	A15-A8	A7-A0	(D7-D0) ⁽³⁾	
Enable QPI	38h					
Block Erase(4KB)	20h	A23-A16	A15-A8	A7-A0		
Block Erase(32KB)	52h	A23-A16	A15-A8	A7-A0		



7.1 Instruction Set Tables

Table 7-2. Instruction Set Table 1 (SPI instruction)⁽¹⁾

Block Erase(64KB)	D8h	A23-A16	A15-A8	A7-A0		
Chip Erase	60h/C7h					
Erase/Program Suspend	75h					
Erase/Program Resume	7Ah					
Deep Power Down	B9h					
Release Deep power down/ Device ID ⁽⁴⁾	ABh	dummy	dummy	dummy	(ID7-ID0) ⁽²⁾	
Read Manufacturer/ Device ID ⁽⁴⁾	90h	00h	00h	00h or 01h	(MID7- MID0)	(DID7-DID0)
Read JEDEC ID	9Fh	(MID7-MID0)	(D7-D0)	(D7-D0)		
Reset Enable	66h					
Reset	99h					
Enter Secured OTP	B1h					
Exit Secured OTP	C1h					
Read Security Register	2Bh	(SC7-SC0) ⁽¹⁰⁾				
Write Security Register	2Fh					
Read Serial Flash Discovery Parameter	5Ah	A23-A16	A15-A8	A7-A0	dummy	(D7-D0)

Table 7-3. Instruction Set Table 2 (Dual SPI Instruction)

INSTRUCTION (CLOCK NUMBER)	(0 – 7)	(8 - 15)	(16 - 23)	(24 - 31)	(32 - 39)	(40 - 47)
Fast Read Dual Output	3Bh	A23-A16	A15-A8	A7-A0	dummy	(D7-D0) ⁽⁶⁾
Fast Read Dual I/O	BBh	A23-A8 ⁽⁵⁾	A7-A0,	(D7-D0,) ⁽⁶⁾		
Read Dual Manufacturer/ Device ID ⁽⁴⁾	92h	0000h	(00h, xxxx) or (01h, xxxx)	(MID7-MID0) (DID7-DID0) ⁽⁶⁾		

Table 7-4. Instruction Set Table 3 (Quad SPI Instruction)

INSTRUCTION (CLOCK NUMBER)	(0 – 7)	(8 - 15)	(16 - 23)	(24 - 31)	(32 - 39)	(4 - 47)
Fast Read Quad Output	6Bh	A23-A16	A15-A8	A7-A0	dummy	(D7-D0) ⁽⁸⁾
Fast Read Quad I/O	EBh	A23-A0, M7-M0 ⁽⁷⁾	(xxx, D7-D0,) ⁽⁹⁾	(D7-D0,) ⁽⁸⁾		
Quad Page Program	33h	A23-A0 (D7-D0,) ⁽⁸⁾				



Table 7-4.	Instruction Set Table 3 (Quad SPI Instruction)
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Read Quad Manufacturer /Device ID ⁽⁴⁾	94h	(00_0000h, xx) or (00_0001h, xx)	(xxxx, MID7-MID0) (xxxx, DID7-DID0) ⁽⁹⁾		
Word Read Quad I/O	E7h	A23-A0, M7-M0 ⁽⁷⁾	(xx, D7-D0)	(D7-D0) ⁽⁸⁾	
Set Burst with Wrap	77h	xxxxxx, W6- W4 ⁽⁷⁾			

Table 7-5. Instruction Set Table 4 (QPI instruction)

INSTRUCTION		BYTE 1	BYTE 2	BYTE 3	BYTE 4	BYTE 5	BYTE 6	BYTE 7	BYTE 8	BYTE 9
(CLOCK NUMBER)		(0 , 1)	(2 , 3)	(4 , 5)	(6 , 7)	(8 , 9)	(10, 11)	(12 , 13)	(14 , 15)	(16 , 17)
Write Enable		06h				·				
Write Enable for Volatile		50h								
Write Disable		04h								
Read Status Register-1		05h	(SR7- SR0) ⁽²⁾							
Read Status Register-2		35h	(SR15- SR8) ⁽²⁾		-					
Write Status Register-1 ⁽⁵⁾		01h	(SR7- SR0)	(SR15- SR8)						
Write Status Re	egister-2	31h	(SR15- SR8)							
Fast Read	>80MHz		A23-A16	A15-A8	A7-A0	dummy	dummy	(D7-D0)		
Data	>104MHz	0Bh	A23-A16	A15-A8	A7-A0	dummy	dummy	dummy	(D7- D0)	
Page Program		02h	A23-A16	A15-A8	A7-A0	(D7-D0) ⁽³⁾				
Block Erase(4KB)		20h	A23-A16	A15-A8	A7-A0					
Block Erase(32KB)		52h	A23-A16	A15-A8	A7-A0					
Block Erase(64KB)		D8h	A23-A16	A15-A8	A7-A0					
Chip Erase		60h/ C7h								
Erase/Program	Suspend	75h								
Erase/Program	Resume	7Ah								
Deep Power Do	own	B9h								
Release Deep Power Down		ABh								
Read Manufac	turer/Device ID ⁽⁴⁾	90h	00h	00h	00h or 01h	(MID7- MID0)	(DID7- DID0)			
Read JEDEC ID ⁽⁴⁾		9Fh	(MID7- MID0) Manufacturer	(D7-D0) Memory Type	(D7-D0) Capacity Type					
Enter Security		B1h								
Exit Security		C1h								



Table 7-5. Instruction Set Table 4 (QPI instruction)

Read Security Register		2Bh	(SC7- SC0) ⁽¹⁰⁾							
Write Security Register		2Fh								
Fast Read Quad I/O	>80MHz	EBh	A23-A16	A15-A8	A7-A0	(M7-M0)	dummy	(D7-D0)		
	>104MHz		A23-A16	A15-A8	A7-A0	(M7- M0)	dummy	dummy	(D7- D0)	
Reset Enable		66h		•			•	•		
Reset		99h								
Disable QPI		FFh								
Burst Read with Wrap	>80MHz	0Ch	A23-A16	A15-A8	A7-A0	dummy	dummy	(D7-D0)		
	>104MHz		A23-A16	A15-A8	A7-A0	dummy	dummy	dummy	(D7- D0)	
Set Read Parameter		C0h	P7-P0							
Quad Page Program		33h	A23-A16	A15-A8	A7-A0	(D7-D0)				

Notes:

Data bytes are shifted with Most Significant Bit first. Byte fields with data in parenthesis "()" indicate data being read from the device 1 on the IO pin.

SR = status register, The Status Register contents and Device ID will repeat continuously until CS terminates the instruction. 2.

At least one byte of data input is required for Page Program, Quad Page Program and Program Security Register, up to 256 bytes 3. of data input. If more than 256 bytes of data are sent to the device, the addressing will wrap to the beginning of the page and overwrite previously sent data.

4. See Manufacturer and Device Identification table for Device ID information.

5. **Dual Input Address** IO0 = A22, A20, A18, A16, A14, A12, A10, A8, A6, A4, A2, A0, M6, M4, M2, M0 IO1 = A23, A21, A19, A17, A15, A13, A11, A9, A7, A5, A3, A1, M7, M5, M3, M1 6. Dual Output data

IO0 = (D6, D4, D2, D0) IO1 = (D7, D5, D3, D1)

Quad Input Address 7.

Set Burst with Wrap Input

x, x, W4,	х
x, x, W5,	х
x, x, W6,	х
x, x, x	х
	x, x, W4, x, x, W5, x, x, W6, x, x, x

- Quad Input/ Output Data 8. IO0 = (D4, D0...)IO1 = (D5, D1...) IO2 = (D6, D2...)
 - IO3 = (D7, D3...)
- Fast Read Quad I/O Data Output 9. $\begin{array}{l} | 00 = (x, x, x, x, D4, D0...) \\ | 01 = (x, x, x, x, D5, D1...) \\ | 02 = (x, x, x, x, D6, D2...) \\ | 03 = (x, x, x, x, D7, D3...) \\ \end{array}$
- 10. SC = security register

7.2 Write Enable (06h)

Write Enable instruction is for setting the Write Enable Latch (WEL) bit in the Status Register. The WEL bit must be set prior to every Program, Erase and Write Status Register instruction. To enter the Write Enable instruction, CS goes low prior to the instruction "06h" into Data Input (SI) pin on the rising edge of SCK, and then driving CS high.







7.3 Write Enable for Volatile Status Register (50h)

This gives more flexibility to change the system configuration and memory protection schemes quickly without waiting for the typical non-volatile bit write cycles or affecting the endurance of the Status Register non-volatile bits. To write the volatile values into the Status Register bits, the Write Enable for Volatile Status Register (50h) instruction must be issued prior to a Write Status Register (01h) instruction. Write Enable for Volatile Status Register instruction (Figure 7-2) will not set the Write Enable Latch (WEL) bit. Once Write Enable for Volatile Status Register is set, a Write Enable instruction should not have been issued prior to setting Write Status Register instruction (01h or 31h). When Write Enable for Volatile Status Register (50h) is set in QPI Mode, the SUS bit (S15) and Reserved bits (S13, S12, S11 and S10) of the Status Register-2 must be driven to high after Write Status Register instruction (01h). Once Read Status Register (05h or 31h) is issued, the read values of SUS bit (S15) and Reserved bits (S13, S12, S11 and S10) of the Status Register-2 are ignored.



Figure 7-2. Write Enable for Volatile Status Register Instruction for SPI Mode (left) and QPI Mode (right)



7.4 Write Disable (04h)

The Write Disable instruction is to reset the Write Enable Latch (WEL) bit in the Status Register. To enter the Write Disable instruction, \overline{CS} goes low prior to the instruction "04h" into Data Input (SI) pin on the rising edge of SCK, and then driving \overline{CS} high. WEL bit is automatically reset write- disable status of "0" after Power-up and upon completion of the every Program, Erase and Write Status Register instructions.





7.5 Read Status Register-1 (05h) and Read Status Register-2 (35h)

The Read Status Register instructions are to read the Status Register. The Read Status Register can be read at any time (even in program/erase/write Status Register and Write Security Register condition). It is recommended to check the BUSY bit before sending a new instruction when a Program, Erase, Write Status Register or Write Status Register operation is in progress.

The instruction is entered by driving \overline{CS} low and sending the instruction code "05h" for Status Register-1 or "35h" for Status Register-2 into the SI pin on the rising edge of SCK. The status register bits are then shifted out on the SO pin at the falling edge of SCK with most significant bit (MSB) first as shown in (Figure 7-4 and Figure 7-5). The Status Register can be read continuously. The instruction is completed by driving \overline{CS} high.







Figure 7-5. Read Status Register Instruction (QPI Mode)



7.6 Write Status Register (01h)

The Write Status Register instruction is to write only non-volatile Status Register-1 bits (SRP0) and Status Register-2 bits (QE and SRP1). All other Status Register bit locations are read-only and will not be affected by the Write Status Register instruction.

A Write Enable instruction must previously have been issued prior to setting Write Status Register Instruction (Status Register bit WEL must equal 1). Once write is enabled, the instruction is entered by driving CS low, sending the instruction code, and then writing the status register data byte as illustrated in Figure 7-6 and Figure 7-7.

The \overline{CS} pin must be driven high after the eighth or sixteenth bit of data that is clocked in. If this is not done the Write Status Register instruction will not be executed. If \overline{CS} is driven high after the eighth clock, the CMP QE and SRP1 bits will be cleared to 0. After \overline{CS} is driven high, the self- timed Write Status Register cycle will commence for a time duration of tw (See AC Characteristics).

While the Write Status Register cycle is in progress, the Read Status Register instruction may still be accessed to check the status of the BUSY bit. The BUSY bit is a 1 during the Write Status Register cycle and a 0 when the cycle is finished and ready to accept other instructions again. When the BUSY bit is asserted, the Write Enable Latch (WEL) bit in Status Register will be cleared to 0.







Figure 7-7. Write Status Register Instruction (QPI Mode)



7.7 Write Status Register-2 (31h)

The Write Status Register-2 instruction is to write only non-volatile Status Register-2 bits (CMP, QE and SRP1).

A Write Enable instruction must previously have been issued prior to setting Write Status Register Instruction (Status Register bit WEL must equal 1). Once write is enabled, the instruction is entered by driving \overline{CS} low, sending the instruction code, and then writing the status register data byte as illustrated in Figure 7-8 and Figure 7-9.

Using Write Status Register-2 (31h) instruction, software can individually access each one-byte status registers via different instructions.







Figure 7-9. Write Status Register-2 Instruction (QPI Mode)



7.8 Read Data (03h)

The Read Data instruction is to read data out from the device. The instruction is initiated by driving the \overline{CS} pin low and then sending the instruction code "03h" with following a 24-bit address (A23- A0) into the SI pin. After the address is received, the data byte of the addressed memory location will be shifted out on the SO pin at the falling edge of SCK with most significant bit (MSB) first. The address is automatically incremented to the next higher address after byte of data is shifted out allowing for a continuous stream of data. This means that the entire memory can be accessed with a single instruction as long as the clock continues. The instruction is completed by driving \overline{CS} high. The Read Data instruction sequence is shown in Figure 7-10. If a Read Data instruction is issued while an Erase, Program or Write Status Register cycle is in process (BUSY=1) the instruction is ignored and will not have any effects on the current cycle. The Read Data instruction allows clock rates from D.C to a maximum of fr (see AC Electrical Characteristics).



Figure 7-10. Read Data Instruction

7.9 Fast Read (0Bh)

The Fast Read instruction is high speed reading mode that it can operate at the highest possible frequency of F_R. The address is latched on the rising edge of the SCK. After the 24-bit address, this is accomplished by adding "dummy" clocks as shown in Figure 7-11. The dummy clocks means the internal circuits require time to set up the initial address. During the dummy clocks, the data value on the SO pin is a "don't care". Data of each bit shifts out on the falling edge of SCK.







7.10 Fast Read in QPI Mode

When QPI mode is enabled, the number of dummy clock is configured by the "Set Read Parameters (C0h)" instruction to accommodate wide range applications with different needs for either maximum Fast Read frequency or minimum data access latency. Depending on the Read Parameter Bit P[4] and P[5] setting, the number of dummy clocks can be configured as either 4, or 6 or 8. The default number of dummy clocks upon power up or after a Reset instruction is 4. (Please refer to Figure 7-12, Figure 7-13 and Figure 7-13).







Figure 7-13. Fast Read instruction (QPI Mode, 104MHz)



7.11 Fast Read Dual Output (3Bh)

By using two pins (IO₀ and IO₁, instead of just IO₀), The Fast Read Dual Output instruction allows data to be transferred from the AT25SL321 at twice the rate of standard SPI devices. The Fast Read Dual Output instruction is ideal for quickly downloading code from Flash to RAM upon power-up or for application that cache code-segments to RAM for execution.

The Fast Read Dual Output instruction can operate at the highest possible frequency of FR (see AC Electrical Characteristics). After the 24-bit address, this is accomplished by adding eight "dummy" clocks as shown in Figure 7-14. The dummy clocks allow the internal circuits additional time for setting up the initial address. During the dummy clocks, the data value on the SO pin is a "don't care". However, the IO₀ pin should be high-impedance prior to the falling edge of the first data out clock.



Figure 7-14. Fast Read Dual Output instruction (SPI Mode)



7.12 Fast Read Quad Output (6Bh)

By using four pins (IO₀, IO₁, IO₂, and IO₃), The Fast Read Quad Output instruction allows data to be transferred from the AT25SL321 at four times the rate of standard SPI devices. A Quad enable of Status Register-2 must be executed before the device will accept the Fast Read Quad Output instruction (Status Register bit QE must equal 1).

The Fast Read Quad Output instruction can operate at the highest possible frequency of FR (see AC Electrical Characteristics). This is accomplished by adding eight "dummy" clocks after the 24- bit address as shown in Figure 7-15. The dummy clocks allow the internal circuits additional time for setting up the initial address. During the dummy clocks, the data value on the SO pin is a "don't care". However, the IO₀ pin should be high-impedance prior to the falling edge of the first data out clock.





7.13 Fast Read Dual I/O (BBh)

The Fast Read Dual I/O instruction reduces cycle overhead through double access using two IO pins: IOo and IO1.

Continuous read mode

The Fast Read Dual I/O instruction can further reduce cycle overhead through setting the Mode bits (M7-0) after the input Address bits (A23-0). The upper nibble of the Mode (M7-4) controls the length of the next Fast Read Dual I/O instruction through the inclusion or exclusion of the first byte instruction code. The lower nibble bits of the Mode (M3-0) are don't care ("X"), However, the IO pins should be high-impedance prior to the falling edge of the first data out clock.



If the Mode bits (M7-0) equal "Ax" hex, then the next Fast Dual I/O instruction (after \overline{CS} is raised and then lowered) does not require the instruction (BBh) code, as shown in Figure 7-16 and Figure 7-17. This reduces the instruction sequence by eight clocks and allows the address to be immediately entered after \overline{CS} is asserted low. If Mode bits (M7-0) are any value other "Ax" hex, the next instruction (after \overline{CS} is raised and then lowered) requires the first byte instruction code, thus returning to normal operation. A Mode Bit Reset can be used to reset Mode Bits (M7-0) before issuing normal instructions.











7.14 Fast Read Quad I/O (EBh)

The Fast Read Quad I/O instruction reduces cycle overhead through quad access using four IO pins: IO₀, IO₁, IO₂, and IO₃. The Quad Enable bit (QE) of Status Register-2 must be set to enable the Fast read Quad I/O Instruction.

Continuous read mode

The Fast Read Quad I/O instruction can further reduce instruction overhead through setting the Mode bits (M7-0) with following the input Address bits (A23-0), as shown in Figure 7-18. The upper nibble of the Mode (M7-4) controls the length of the next Fast Read Quad I/O instruction through the inclusion or exclusion of the first byte instruction code. The lower nibble bits of the Mode (M3-0) are don't care ("X"). However, the IO pins should be high-impedance prior to the falling edge of the first data out clock.

If the Mode bits (M7-0) equal "Ax" hex, then the next Fast Read Quad I/O instruction (after \overline{CS} is raised and then lowered) does not require the EBh instruction code, as shown in Figure 7-19. This reduces the instruction sequence by eight clocks and allows the address to be immediately entered after \overline{CS} is asserted low. If the Mode bits (M7-0) are any value other than "Ax" hex, the next instruction (after \overline{CS} is raised and then lowered) requires the first byte instruction code, thus retuning normal operation. A Mode Bit Reset can be used to reset Mode Bits (M7-0) before issuing normal instructions.

